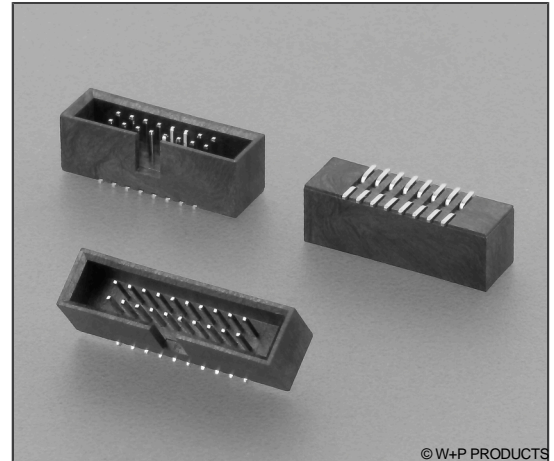


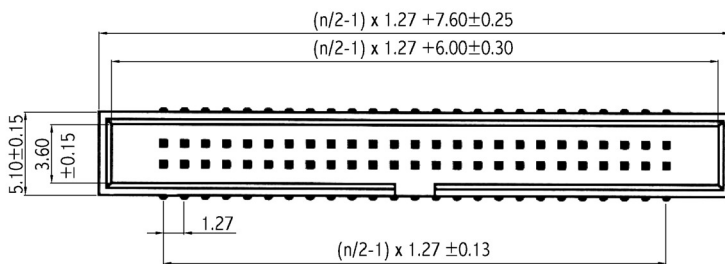
### Technische Daten / Technical Data

|  |  |
|--|--|
| Isolierkörper<br><i>Insulator</i>                    | Thermoplast, nach UL94 V-0<br><i>Thermoplastic, rated UL94 V-0</i> |
| Kontaktmaterial<br><i>Contact Material</i>           | Messing<br><i>Brass</i>  |
| Kontaktoberfläche<br><i>Contact Surface</i>          | Vergoldet<br><i>Gold plated</i>                                    |
| Durchgangswiderstand<br><i>Contact Resistance</i>    | < 20 mΩ  |
| Isolationswiderstand<br><i>Insulation Resistance</i> | > 1000 MΩ  |
| Spannungsfestigkeit<br><i>Test Voltage</i>           | 500 V AC   |
| Nennstrom<br><i>Current Rating</i>                   | 1 A  |
| Temperaturbereich<br><i>Temperature Range</i>        | -40 °C ... +105 °C   |
| Verarbeitung<br><i>Processing</i>                    | Reflow-Lötverfahren<br><i>Reflow soldering</i>                     |

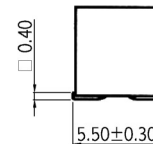
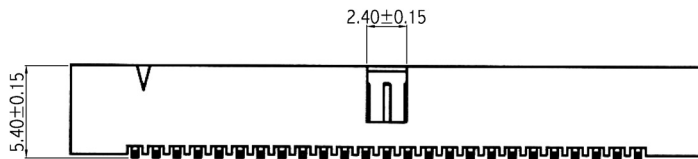
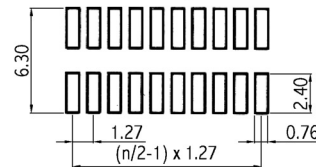


© W+P PRODUCTS

Passende Gegenstecker:  
Compatible Connectors:  
**376**



### Recommended PCB Layout



### Series

**3360**

### Contacts\*

**016**

010-100

### Plating

**00**

00 Vergoldet  
Gold plated

### Packaging\*

**ST**

ST  
PPST  
PPTR (Option)

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** - please replace by your specifications.

### Lieferformen / Packaging Options:

**ST** In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads

**PPST** In Stangen mit P&P-Pads / In tubes with P&P-Pads

**PPTR (Option)** Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

## Informationen zum Reflow-Lötverfahren Reflow Soldering Information

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft                    | Kennwert      |
|--------------------------------------|---------------|
| Temperatur Minimum $T_{Smin}$        | 150 °C        |
| Temperatur Maximum $T_{Smax}$        | 200 °C        |
| Dauer $T_{Smin} - T_{Smax}$          | 60 – 180s     |
| Temperatur Lötbereich $T_L$          | 217 °C        |
| Verweildauer oberhalb $T_L$          | 60 – 180s     |
| Ramp-Up Rate $T_{Smax} - T_P$        | max. 3 °C / s |
| Höchsttemperatur $T_P$               | 260±5 °C      |
| Dauer Höchsttemperatur               | 20 – 40s      |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s      |
| Dauer 25 °C – Höchsttemperatur $T_P$ | max. 8m       |

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature                      | Key Values    |
|--------------------------------------|---------------|
| Minimum Temperature $T_{Smin}$       | 150 °C        |
| Maximum Temperatur $T_{Smax}$        | 200 °C        |
| Duration $T_{Smin} - T_{Smax}$       | 60 – 180s     |
| Soldering Range Temperature $T_L$    | 217 °C        |
| Duration above $T_L$                 | 60 – 180s     |
| Ramp-Up Rate $T_{Smax} - T_P$        | max. 3 °C / s |
| Peak Temperature $T_P$               | 260±5 °C      |
| Duration Peak Temperature            | 20 – 40s      |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s      |
| Duration 25°C - Peak Temp. $T_P$     | max. 8min     |

